

RE

10-09-2003



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Atty. Dkt. No.: AMK-BK-00001

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

**PARK, Sung Soon;
JANG, Sang Jae;
LEE, Choon Heung;
LEE, Seon Goo;
SOHN, Eun Sook; and
PARK, Sung Su**

Additional name(s) of conveying party(ies) attached?

☐ Yes ☒ No

2. Name and address of receiving party(ies):

Name: **Amkor Technology, Inc.**

Street Address: **1900 South Price Road**

City/State/Zip: **Chandler, AZ 85248-1604**

Additional name(s) & address(es) attached?

☐ Yes ☒ No

22264 U.S. PTO
10/672886
09/26/03

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other

Execution Date: September 26, 2003

4. Application number(s) or patent number(s):

10/672886

If this document is being filed together with a new application, the execution date of the application is: September 26, 2003

A. Patent Application No.(s):

B. Patent No.(s):

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name:

James E. Parsons, Esq.
Bever, Hoffman & Harms, LLP
2099 Gateway Place, Suite 320
San Jose, CA 95110-1017

6. Total number of applications and patents involved: [ONE]

7. Total fee (37 CFR 3.41) \$40.00

- ☐ Enclosed
☒ Authorized to be charged to deposit account

8. Deposit account number: 50-0574
(Attorney Docket No.: AMK-BK-00001)

10/06/2003 ECOPER 00000205 500574 10672886

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9. Signature.

James E. Parsons

Name of Person Signing

Signature

9/26/2003

Date

Total number of pages including cover sheet, attachments, and document: [3]

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PATENT
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ASSIGNMENT

For good and valuable consideration, receipt of which is hereby acknowledged, we

Sung Soon Park of 213-6 #301, Myeonmok1-dong, Jungnang-gu, Seoul, Republic of Korea
 Sang Jae Jang of 101-1803 Hyundai Apt., Hwayang-dong 234, Gwangjin-gu, Seoul, Republic of Korea
 Choon Heung Lee of 106-1101 Hyundai Apt., Tanbeol-dong 40, Gwangju-si, Gyeonggi-do, Republic of Korea
 Seon Goo Lee of 12-870 Miseong Apt., Wolgye 3-dong, Nowon-gu, Seoul, Republic of Korea
 Eun Sook Sohn of 101-607 Daewoo 1st Apt., Seongsu 2-ga 3-dong, 279-50 Seongdong-gu, Seoul, Republic of Korea
 Sung Su Park of 45-33, Hwayang-dong, Gwangjin-gu, Seoul, Republic of Korea

hereby sell, assign and transfer to **Amkor Technology, Inc.**, a Delaware corporation, having a place of business at 1900 South Price Road Chandler, AZ 85248-1604, its successors and assigns, the entire right, title and interest throughout the world in our invention in

SEMICONDUCTOR PACKAGE STRUCTURE REDUCING WARPAGE AND MANUFACTURING METHOD THEREOF

for which we will execute a United States patent application on or about the date of this assignment, and all patent applications and patents of every country for said invention, including divisions, reissues, continuations and extensions thereof, and all rights of priority resulting from the filing of said applications; we authorize the above-named assignee to apply for patents of foreign countries for said invention, and to claim all rights of priority without further authorization from us; we agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignee, their successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in all countries; and we request the Commissioner of Patents and Trademarks to issue all patents granted for said invention to the above-named assignee, its successors and assigns.

Executed this 26th day of Sept., 2003.

Mr. Park
Sung Soon Park

Witness signature: _____

Do Hyun Na
 Do Hyun Na

Executed this 26th day of Sep, 2003.

Sang Jae Jang
 Sang Jae Jang

Witness signature: _____

Do Hyun Na
 Do Hyun Na

Executed this 26th day of September, 2003.

Choon Heung Lee
 Choon Heung Lee

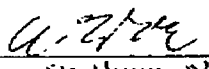
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Do Hyun Na
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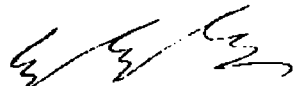
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Seon Goo Lee

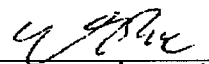
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Do Hyun Na

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Eun Sook Sohn

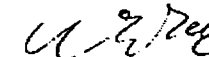
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Sung Su Park

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Do Hyun Na